

EPW



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

IWAO NOZAWA ET AL

Application No.: 10/668,377

Art Unit: 1753

Filed: September 24, 2003

For: SOLDER FOR USE ON SURFACES COATED WITH NICKEL BY
ELECTROLESS PLATING

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Pursuant to the requirements of 37 CFR §§1.56 and 1.97, the attention of the Examiner is directed to the documents listed on the attached Form PTO-1449. A copy of each of the listed documents which is not a U.S. patent document is attached. Neither this Statement nor the listing of these documents on Form PTO-1449 is an admission that these documents are prior art as to the Applicants or a representation that a search has been made or that no more pertinent documents exist.

The Applicants' representative certifies that the listed documents were cited in a communication from the European Patent

Office in a counterpart foreign patent application not more than three months before the filing date of this Information Disclosure Statement. A copy of the European Search Report from the counterpart application is attached as an explanation of the relevance of the documents.

The Applicants respectfully request that the listed documents be considered by the Examiner and made of record in the referenced patent application.

Respectfully submitted,



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Date: May 3, 2004

Form PTO-1449 (modified)
List of Patent and Publications For
Applicant's Information Disclosure
Statement
(use several sheets if necessary)

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Atty. Docket. No.:
1052

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U.S. PATENT DOCUMENTS

Exr's Initial		Document No.							Date	Name	Class	Sub class	Filing Date
	AA	6	0	3	3	4	8	8	3/7/2000	An et al	148	24	10/30/97
	AB	6	3	0	7	1	6	0	10/23/01	Mei et al	174	256	10/29/98
	AC												
	AD												
	AE												

FOREIGN PATENT DOCUMENTS

		Document No.							Date	Country	Class	Sub class	Translation	
													Yes	No
	AF	0	6	5	2	0	7	2	5/10/95	EP				
	AG													
	AH													

OTHER ART (Including author, title, date pertinent pages, etc.)

	AI	Shi-Wei Ricky Lee et al, "Assessment on the Effects of Electronless Nickel Plating on the Reliability of Solder Ball Attachment to the Bond Pads of PBGA Substrate", 2000 Proceedings, 50th Electronic Components and Technology Conference, ECTC 2000, Las Vegas, May 21 - 24, 2000. Proceedings of the Electronic Components and Technology Conference, New York; IEEE US, vol. Conf. 50, May 21, 2000, pages 868 - 873											
	AJ	Zequn Mei et al, "Brittle Interfacial Fracture of PBGA Packages Soldered on Electroless Nickel/Immersion Gold", Electronic Components & Technology Conference, 1998, 48th IEEE Seattle, Wa. May 25 - 28, 1998, New York, IEEE, US May 25, 1998, pages 952 - 961											
	AK	Patent Abstracts of Japan, vol. 1999, No. 04, April 30, 1999, Abstract of JP 11-00791 A, published on 1/6/99											
	AL	Patent Abstracts of Japan, vol. 1995, no. 11, December 26, 1995, Abstract of JP 07-195189 A, published on 8/1/95											
	AM	Patent Abstracts of Japan, vol. 2000, no. 13, February 5, 2001, Abstract of JP 2000-277895 A, published on 10/6/2000											

Examiner

Date considered:

EXAMINER: Initial if reference considered, no matter whether citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.